

74HC4538; 74HCT4538

Dual retriggerable precision monostable multivibrator

Rev. 03 — 8 June 2009

Product data sheet

1. General description

The 74HC4538; 74HCT4538 are high-speed Si-gate CMOS devices and are pin compatible with Low-power Schottky TTL (LSTTL). They are specified in compliance with JEDEC standard no. 7A.

The 74HC4538; 74HCT4538 are dual retriggerable-resetable monostable multivibrators. Each multivibrator has an active LOW trigger/retrigger input ($\overline{nA}$), an active HIGH trigger/retrigger input (nB), an overriding active LOW direct reset input ($\overline{nCD}$), an output (nQ) and its complement ($\overline{nQ}$), and two pins ($nREXT/CEXT$ and $nCEXT$) for connecting the external timing components C_{EXT} and R_{EXT} . Typical pulse width variation over the specified temperature range is $\pm 0.2\%$.

The multivibrator may be triggered by either the positive or the negative edges of the input pulse. The duration and accuracy of the output pulse are determined by the external timing components C_{EXT} and R_{EXT} . The output pulse width (t_W) is equal to $0.7 \times R_{EXT} \times C_{EXT}$. The linear design techniques guarantee precise control of the output pulse width. A LOW level at $\overline{nCD}$ terminates the output pulse immediately. Schmitt trigger action on pins $\overline{nA}$ and nB makes the circuit highly tolerant of slower rise and fall times.

2. Features

- Tolerant of slow trigger rise and fall times
- Separate reset inputs
- Triggering from falling or rising edge
- Multiple package options
- ESD protection:
 - ◆ HBM JESD22-A114E exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and from $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC4538N	−40 °C to +125 °C	DIP16	plastic dual in-line package; 16-leads (300 mil)	SOT38-4
74HCT4538N				
74HC4538D	−40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4538D				
74HC4538DB	−40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT4538DB				
74HC4538PW	−40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HCT4538PW				

4. Functional diagram

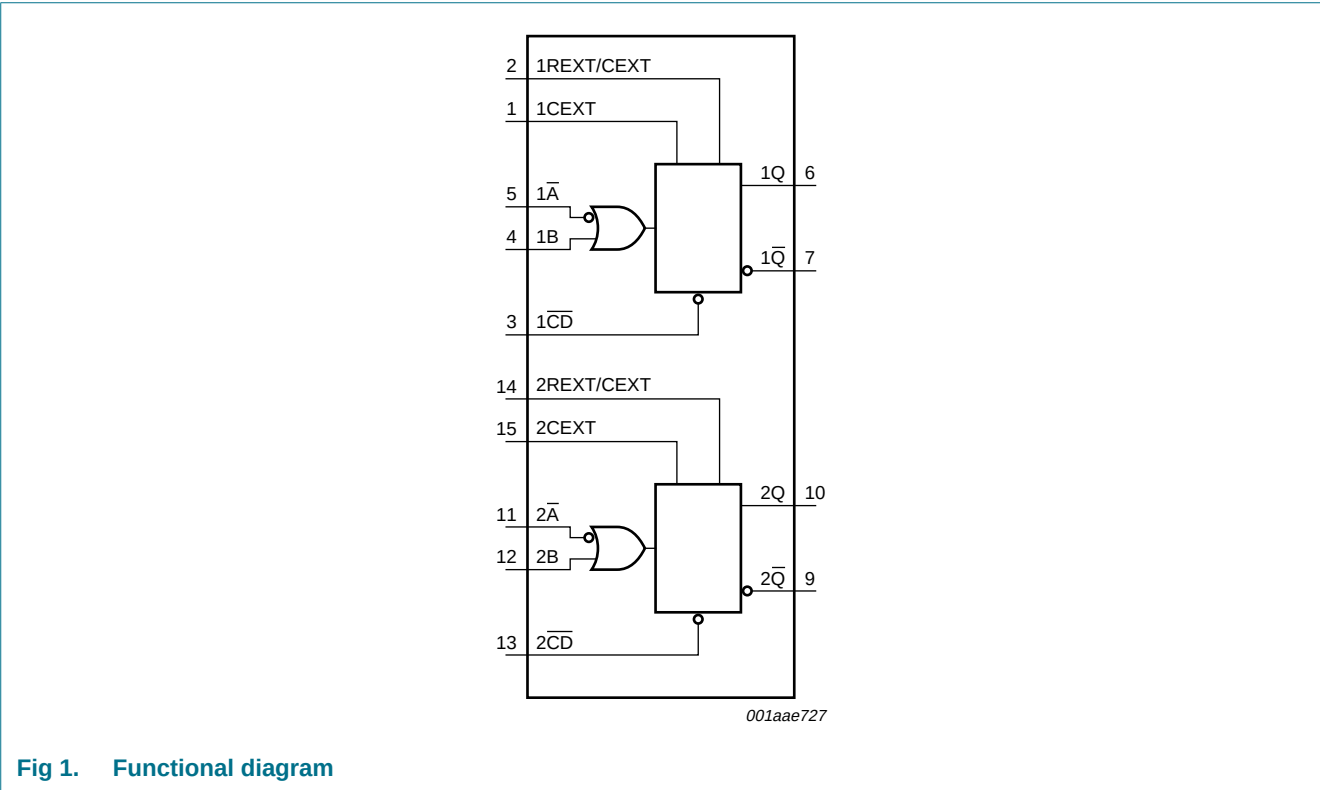


Fig 1. Functional diagram

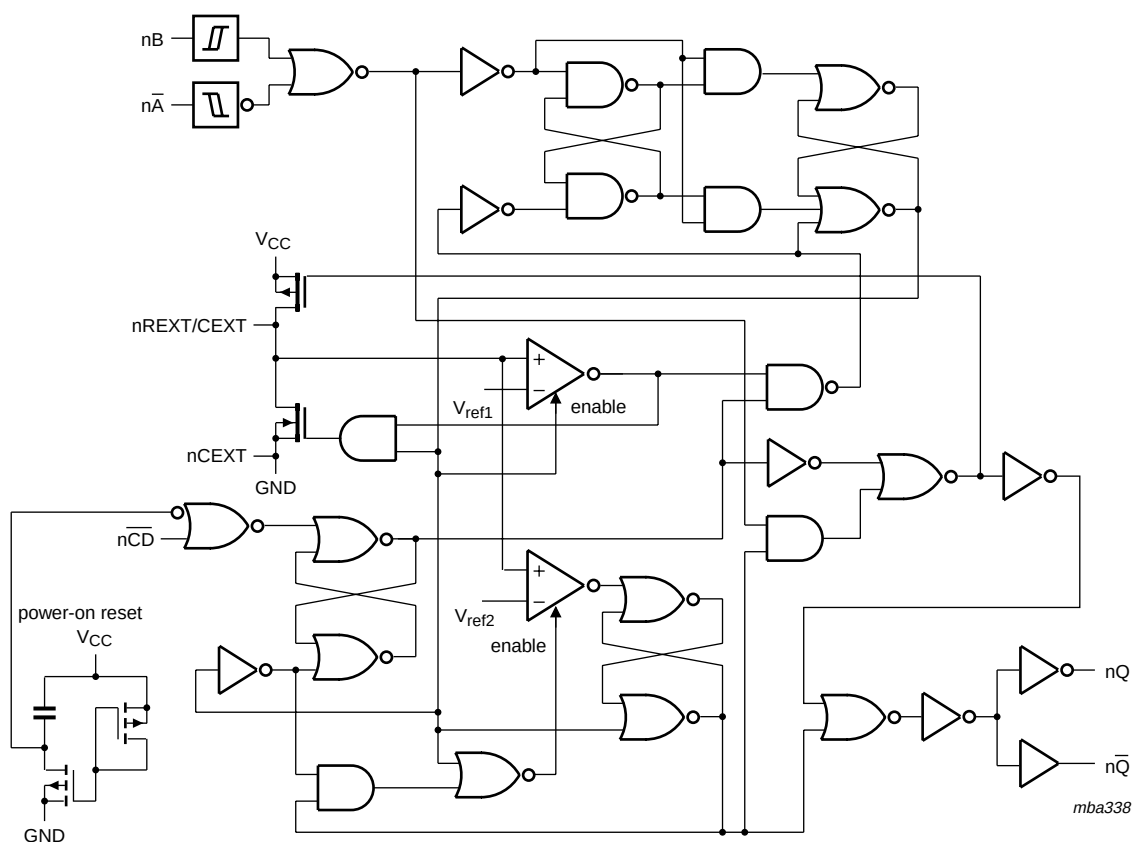


Fig 2. Logic diagram (one multivibrator)

5. Pinning information

5.1 Pinning

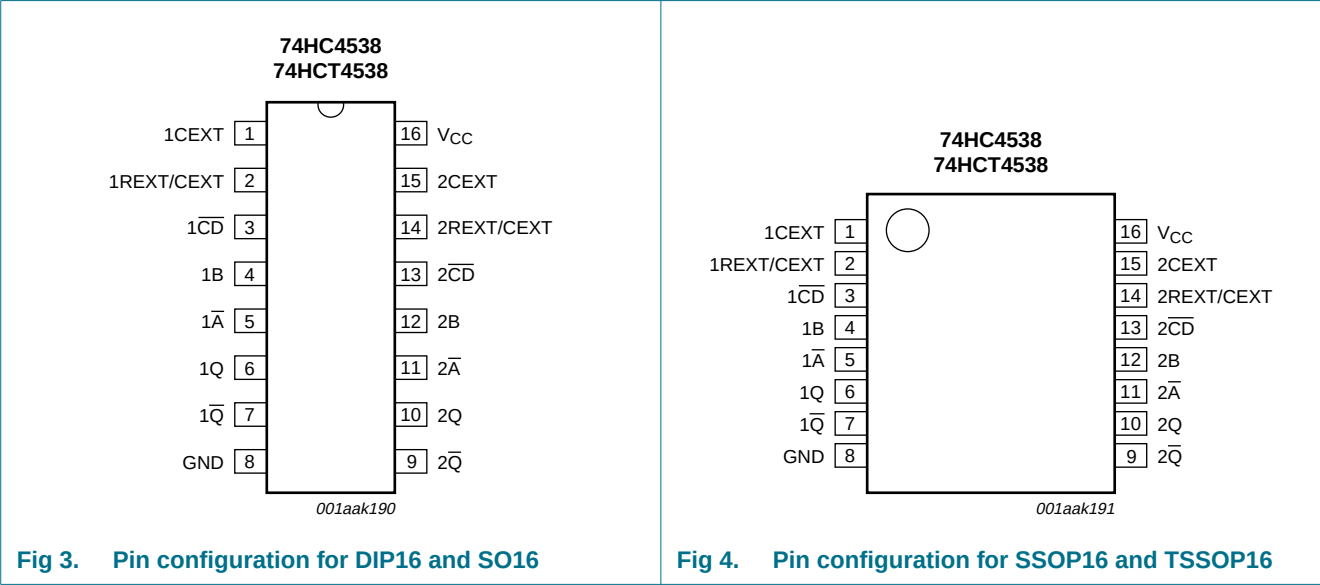


Fig 3. Pin configuration for DIP16 and SO16

Fig 4. Pin configuration for SSOP16 and TSSOP16

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1CEXT, 2CEXT	1, 15	external capacitor connection (always connected to ground)
1REXT/CEXT, 2REXT/CEXT	2, 14	external capacitor/resistor connection
1CD, 2CD	3, 13	direct reset input (active LOW)
1B, 2B	4, 12	input (LOW to HIGH triggered)
1A, 2A	5, 11	input (HIGH to LOW triggered)
1Q, 2Q	6, 10	output
1Q, 2Q	7, 9	complementary output (active LOW)
GND	8	ground (0 V)
V _{CC}	16	supply voltage

6. Functional description

Table 3. Function table

Inputs			Outputs	
nA	nB	nCD	nQ	nQ
↓	L	H		
H	↑	H		
X	X	L	L	H

- [1] H = HIGH voltage level; L = LOW voltage level; X = don't care;
↑ = positive-going transition; ↓ = negative-going transition;
-  = one HIGH level output pulse, with the pule width determined by C_{EXT} and R_{EXT};
-  = one LOW level output pulse, with the pulse width determined by C_{EXT} and R_{EXT}.

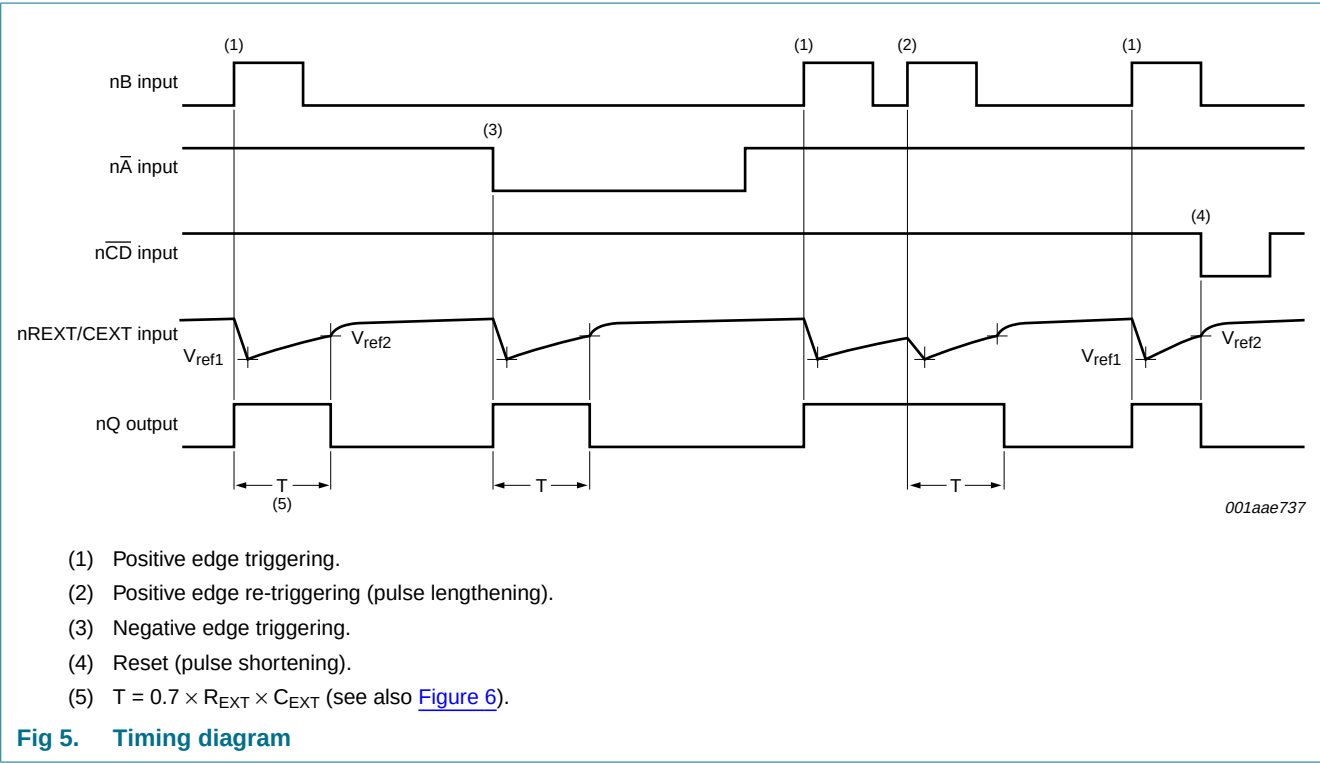


Fig 5. Timing diagram

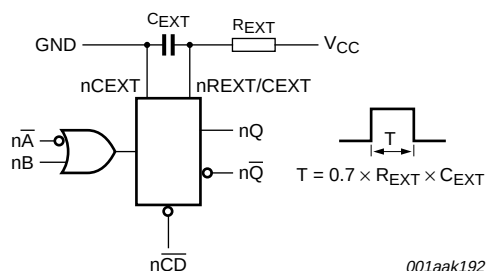


Fig 6. Connection of the external timing components R_{EXT} and C_{EXT}

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	supply voltage		−0.5	+7.0	V
I _{IK}	input clamping current	V _I < −0.5 V or V _I > V _{CC} + 0.5 V	[1] -	±20	mA
I _{OK}	output clamping current	V _O < −0.5 V or V _O > V _{CC} + 0.5 V	[1] -	±20	mA
I _O	output current	V _O = −0.5 V to V _{CC} + 0.5 V	-	±25	mA
I _{CC}	supply current		-	+50	mA
I _{GND}	ground current		−50	-	mA
T _{stg}	storage temperature		−65	+150	°C
P _{tot}	total power dissipation	T _{amb} = −40 °C to +125 °C			
		DIP16 package	[2] -	750	mW
		SO16 package	[3] -	500	mW
		(T)SSOP16 package	[4] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- [2] P_{tot} derates linearly with 12 mW/K above 70 °C.
- [3] P_{tot} derates linearly with 8 mW/K above 70 °C.
- [4] P_{tot} derates linearly with 5.5 mW/K above 60 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC4538			74HCT4538			Unit
			Min	Typ	Max	Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V _I	input voltage		0	-	V _{CC}	0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	-	+125	-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	-	-	-	ns/V
		V _{CC} = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	-	-	-	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
74HC4538										
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = −20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = −20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = −20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = −4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	I _O = −5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
		V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
I _I	input leakage current	I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
		V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1	-	±1	μA
		pin nREXT/CEXT; V _I = 2.0 V or GND; other inputs at V _{CC} or GND; V _{CC} = 6.0 V [4]	-	-	±0.5	-	±5	-	±10	μA

Table 6. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 6.0$ V	-	-	8.0	-	80	-	160	μ A
C_I	input capacitance		-	3.5	-	-	-	-	-	pF
74HCT4538										
V_{IH}	HIGH-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V_{IL}	LOW-level input voltage	$V_{CC} = 4.5$ V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V_{OH}	HIGH-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5$ V								
		$I_O = -20$ μ A	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -4.0$ mA	3.98	4.32	-	3.84	-	3.7	-	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL} ; $V_{CC} = 4.5$ V								
		$I_O = 20$ μ A; $V_{CC} = 4.5$ V	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0$ mA; $V_{CC} = 4.5$ V	-	0.15	0.26	-	0.33	-	0.4	V
I_I	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 5.5$ V	-	-	± 0.1	-	± 1	-	± 1	μ A
		pin nREXT/CEXT; $V_I = 2.0$ V or GND; other inputs at V_{CC} or GND; $V_{CC} = 5.5$ V [1]	-	-	± 0.5	-	± 5	-	± 10	μ A
I_{CC}	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	-	8.0	-	80	-	160	μ A
ΔI_{CC}	additional supply current	$V_I = V_{CC} - 2.1$ V; $I_O = 0$ A; other inputs at V_{CC} or GND; $V_{CC} = 4.5$ V to 5.5 V								
		pin nA, nB	-	50	180	-	225	-	245	μ A
		pin nCD	-	65	234	-	293	-	319	μ A
C_I	input capacitance		-	3.5	-	-	-	-	-	pF

[1] This measurement can only be carried out after a trigger pulse is applied.

10. Dynamic characteristics

Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
74HC4538										
t _{PLH}	LOW to HIGH propagation delay	n $\overline{A}$, nB to nQ; see Figure 7								
		V _{CC} = 2.0 V	-	85	265	-	330	-	400	ns
		V _{CC} = 4.5 V	-	31	53	-	66	-	80	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	27	-	-	-	-	-	ns
		V _{CC} = 6.0 V	-	25	45	-	56	-	68	ns
		n $\overline{CD}$ to n $\overline{Q}$; see Figure 7								
		V _{CC} = 2.0 V	-	83	265	-	340	-	400	ns
		V _{CC} = 4.5 V	-	30	53	-	68	-	80	ns
		V _{CC} = 6.0 V	-	24	45	-	58	-	68	ns
t _{PHL}	HIGH to LOW propagation delay	n $\overline{A}$, nB to n $\overline{Q}$; see Figure 7								
		V _{CC} = 2.0 V	-	83	265	-	330	-	400	ns
		V _{CC} = 4.5 V	-	30	53	-	66	-	80	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	27	-	-	-	-	-	ns
		V _{CC} = 6.0 V	-	24	45	-	56	-	68	ns
		n $\overline{CD}$ to nQ; see Figure 7								
		V _{CC} = 2.0 V	-	80	265	-	330	-	400	ns
		V _{CC} = 4.5 V	-	29	53	-	66	-	80	ns
		V _{CC} = 6.0 V	-	23	45	-	56	-	68	ns
t _t	transition time	nQ and n $\overline{Q}$; see Figure 7 [2]								
		V _{CC} = 2.0 V	-	19	75	-	95	-	119	ns
		V _{CC} = 4.5 V	-	7	15	-	19	-	22	ns
		V _{CC} = 6.0 V	-	6	13	-	16	-	19	ns

Table 7. Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
t_W	pulse width	n $\overline{A}$ LOW; see Figure 8								
		$V_{CC} = 2.0\text{ V}$	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5\text{ V}$	16	6	-	20	-	24	-	ns
		$V_{CC} = 6.0\text{ V}$	14	5	-	17	-	20	-	ns
		nB HIGH; see Figure 8								
		$V_{CC} = 2.0\text{ V}$	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5\text{ V}$	16	6	-	20	-	24	-	ns
		$V_{CC} = 6.0\text{ V}$	14	5	-	17	-	20	-	ns
		n $\overline{CD}$ LOW; see Figure 8								
		$V_{CC} = 2.0\text{ V}$	80	19	-	100	-	120	-	ns
		$V_{CC} = 4.5\text{ V}$	16	7	-	20	-	24	-	ns
		$V_{CC} = 6.0\text{ V}$	14	6	-	17	-	20	-	ns
t_{rec}	recovery time	nQ and n $\overline{Q}$ HIGH or LOW; see Figure 8								
		$V_{CC} = 5.0\text{ V};$ $C_{EXT} = 0.1\text{ }\mu\text{F};$ $R_{EXT} = 10\text{ k}\Omega$	630	700	770	602	798	595	805	μs
		n $\overline{CD}$ to n $\overline{A}$, nB; see Figure 8								
		$V_{CC} = 2.0\text{ V}$	35	6	-	45	-	55	-	ns
		$V_{CC} = 4.5\text{ V}$	7	2	-	9	-	11	-	ns
		$V_{CC} = 6.0\text{ V}$	6	2	-	8	-	9	-	ns
t_{rtrig}	retrigger time	n $\overline{A}$, nB; see Figure 8 ; $X = C_{EXT} / (4.5 \times V_{CC})$								
		$V_{CC} = 2.0\text{ V}$	-	455 + X	-	-	-	-	-	ns
		$V_{CC} = 4.5\text{ V}$	-	80 + X	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	55 + X	-	-	-	-	-	ns
R_{EXT}	external timing resistor	$V_{CC} = 2.0\text{ V}$	10	-	1000	-	-	-	-	k Ω
		$V_{CC} = 5.0\text{ V}$	2	-	1000	-	-	-	-	k Ω
C_{EXT}	external timing capacitor					no limits				
C_{PD}	power dissipation capacitance	per multivibrator; $V_I = \text{GND to } V_{CC}$	^[3]	-	136	-	-	-	-	pF

Table 7. Dynamic characteristics ...continuedVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

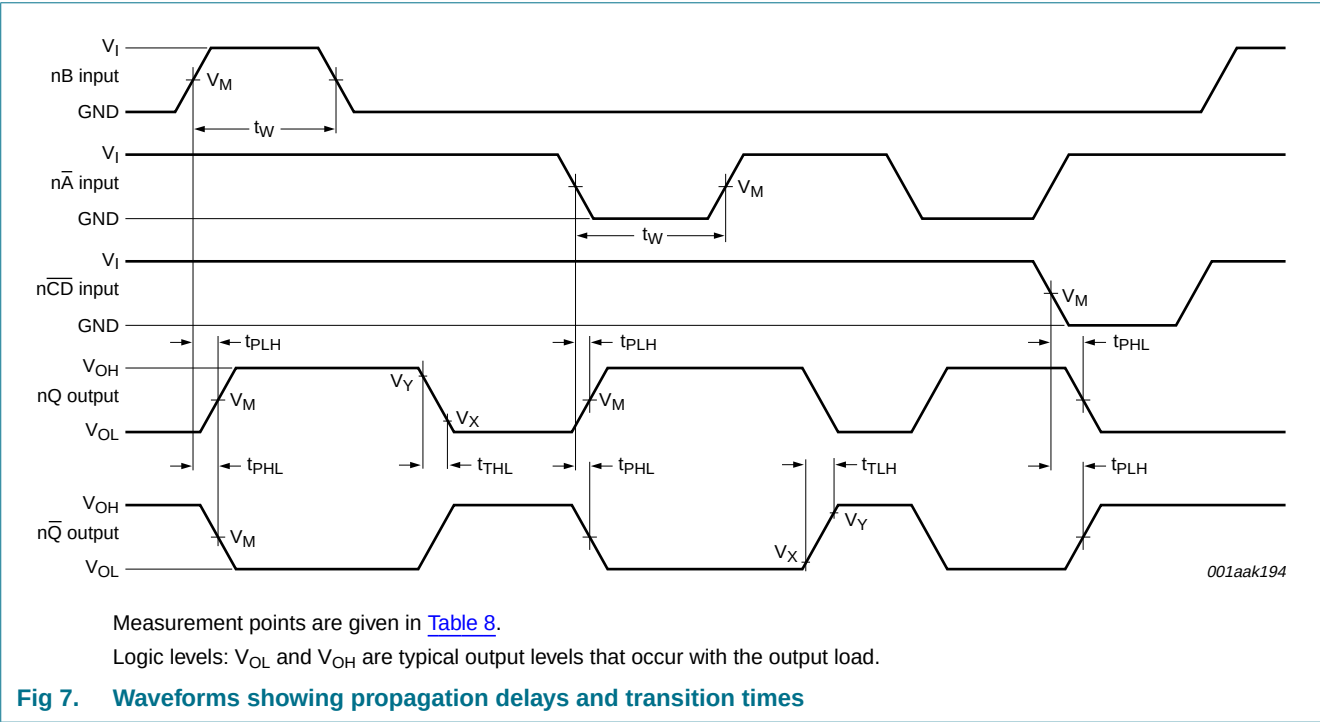
Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
74HCT4538										
t _{PLH}	LOW to HIGH propagation delay	n $\overline{A}$, nB to nQ; see Figure 7								
		V _{CC} = 4.5 V	-	35	60	-	75	-	90	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	30	-	-	-	-	-	ns
		n $\overline{CD}$ to n $\overline{Q}$; see Figure 7								
t _{PHL}	HIGH to LOW propagation delay	n $\overline{A}$, nB to n $\overline{Q}$; see Figure 7								
		V _{CC} = 4.5 V	-	35	60	-	75	-	90	ns
		V _{CC} = 5.0 V; C _L = 15 pF	-	30	-	-	-	-	-	ns
		n $\overline{CD}$ to nQ; see Figure 7								
t _t	transition time	nQ and n $\overline{Q}$; see Figure 7 [2]								
		V _{CC} = 4.5 V	-	7	15	-	19	-	21	ns
t _W	pulse width	n $\overline{A}$ LOW; see Figure 8								
		V _{CC} = 4.5 V	20	11	-	25	-	30	-	ns
		nB HIGH; see Figure 8								
		V _{CC} = 4.5 V	16	5	-	20	-	24	-	ns
		n $\overline{CD}$ LOW; see Figure 8								
		V _{CC} = 4.5 V	20	11	-	25	-	30	-	ns
t _{rec}	recovery time	nQ and n $\overline{Q}$ HIGH or LOW; see Figure 8								
		V _{CC} = 5.0 V; C _{EXT} = 0.1 μF; R _{EXT} = 10 kΩ	630	700	770	602	798	595	805	μs
		n $\overline{CD}$ to n $\overline{A}$, nB; see Figure 8								
t _{trig}	retrigger time	n $\overline{A}$, nB; see Figure 8 ; X = C _{EXT} / (4.5 × V _{CC})								
		V _{CC} = 4.5 V	-	80 + X	-	-	-	-	-	ns
R _{EXT}	external timing resistor	V _{CC} = 5.0 V	2	-	1000	-	-	-	-	kΩ
C _{EXT}	external timing capacitor	V _{CC} = 5.0 V	no limits							

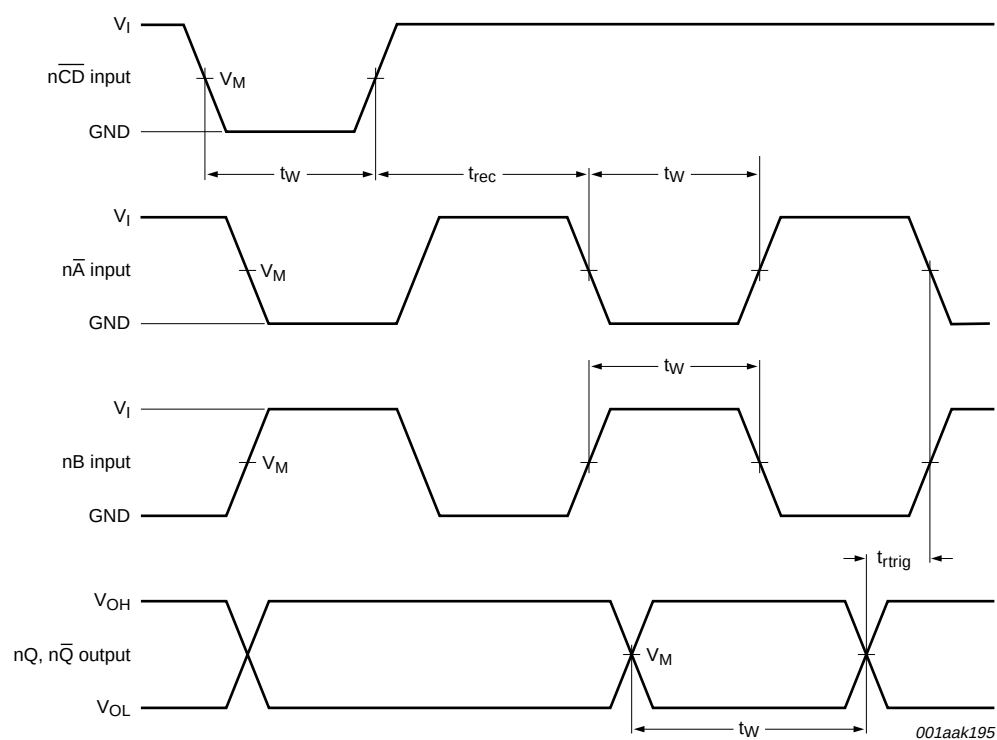
Table 7. Dynamic characteristics ...continued
 Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ ^[1]	Max	Min	Max	Min	Max	
C _{PD}	power dissipation capacitance	per multivibrator; V _I = GND to (V _{CC} – 1.5 V) ^[3]	-	138	-	-	-	-	-	pF

- [1] Typical values are measured at nominal supply voltage (V_{CC} = 3.3 V and V_{CC} = 5.0 V).
- [2] t_t is the same as t_{THL} and t_{TLH}.
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW).
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times \Sigma(C_L \times V_{CC}^2 \times f_o) + 0.48 \times C_{EXT} \times V_{CC}^2 \times f_o + D \times 0.8 \times V_{CC}$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 Σ(C_L × V_{CC}² × f_o) = sum of the outputs;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 D = duty cycle factor in %;
 C_{EXT} = external timing capacitance in pF.

11. Waveforms



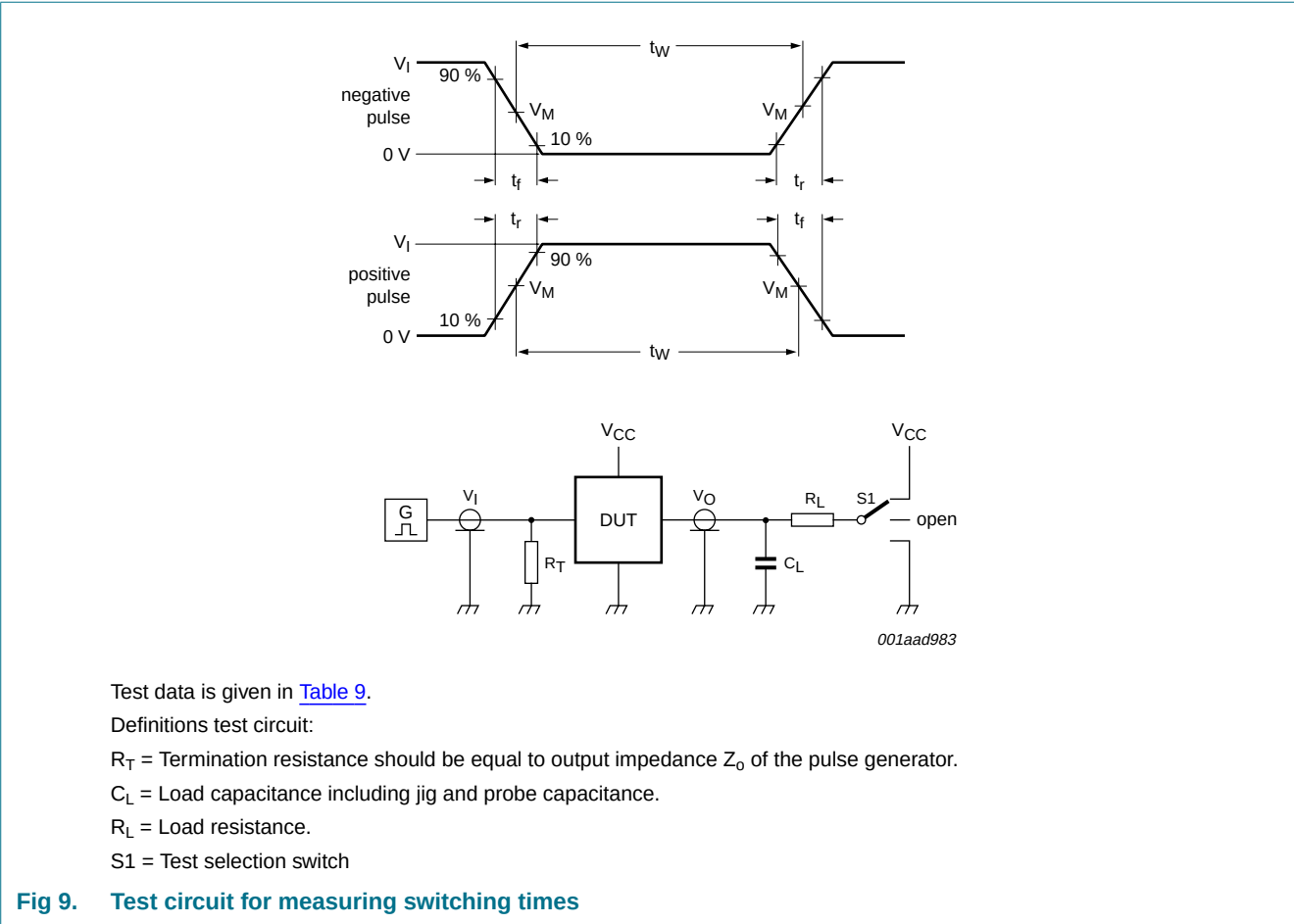


Measurement points are given in [Table 8](#).
Logic levels: V_{OL} and V_{OH} are typical output levels that occur with the output load.

Fig 8. Waveforms showing $\overline{nA}$, nB , nQ , $\overline{nQ}$ pulse widths, recovery and retrigger times

Table 8. Measurement points

Type	Input	Output		
	V_M	V_M	V_X	V_Y
74HC4538	$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$
74HCT4538	1.3 V	1.3 V	$0.1V_{CC}$	$0.9V_{CC}$



Test data is given in [Table 9](#).

Definitions test circuit:

R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

C_L = Load capacitance including jig and probe capacitance.

R_L = Load resistance.

$S1$ = Test selection switch

Fig 9. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}
74HC4538	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open
74HCT4538	3 V	6 ns	15 pF, 50 pF	1 k Ω	open

12. Application information

12.1 Power-down considerations

A large capacitor (C_{EXT}) may cause problems when powering-down the monostable due to energy stored in this capacitor. When a system containing this device is powered-down or rapid decrease of V_{CC} to zero occurs, the monostable may sustain damage, due to the capacitor discharging through the input protection diodes. To avoid this possibility, use a damping diode (D_{EXT}) preferably a germanium or Schottky type diode able to withstand large current surges and connect as shown in [Figure 10](#)

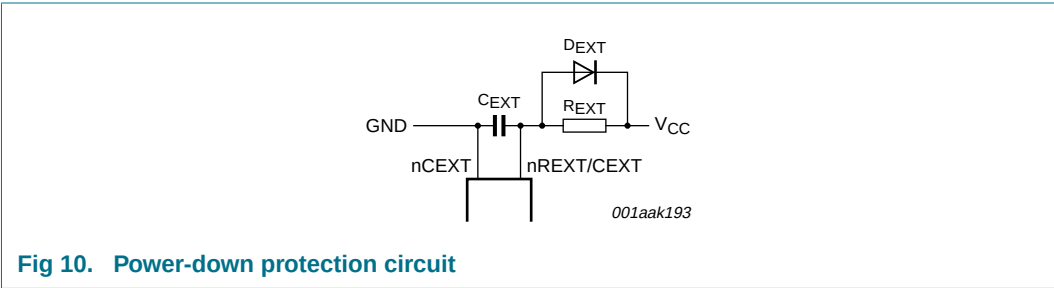


Fig 10. Power-down protection circuit

12.2 Graphs

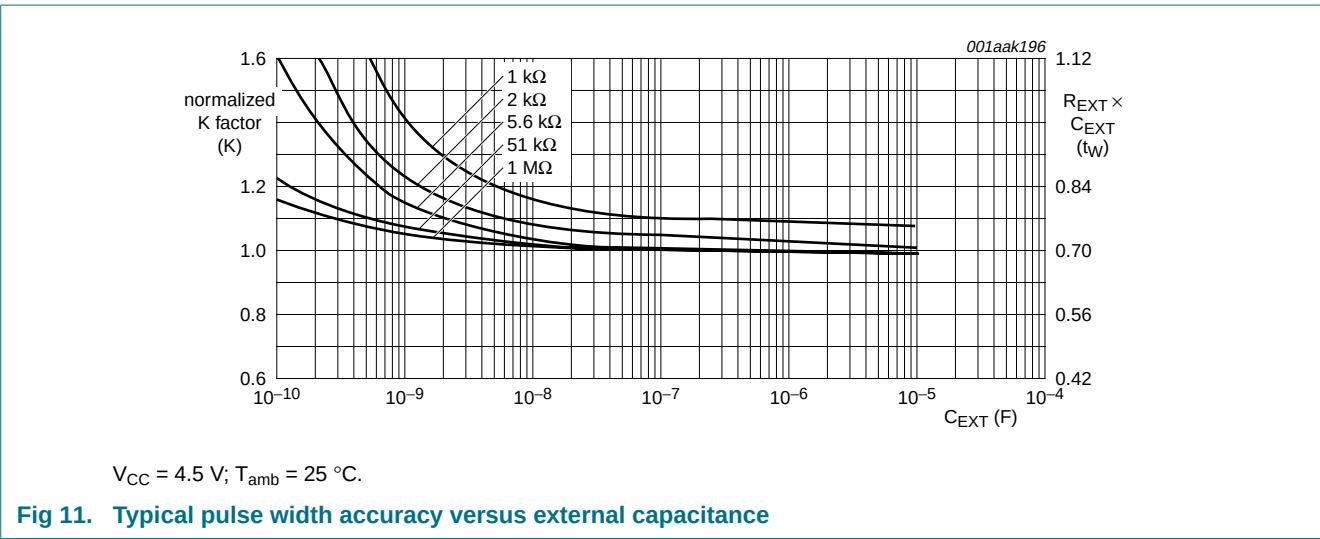
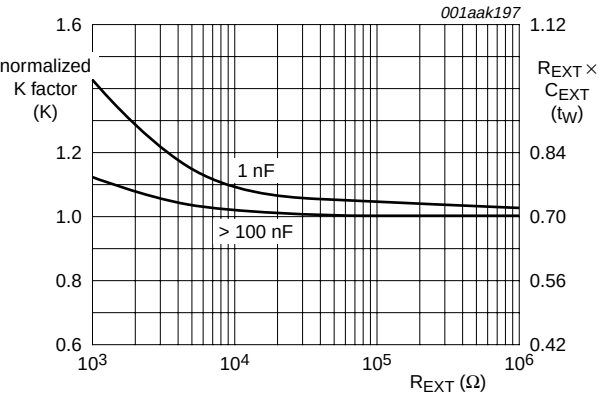
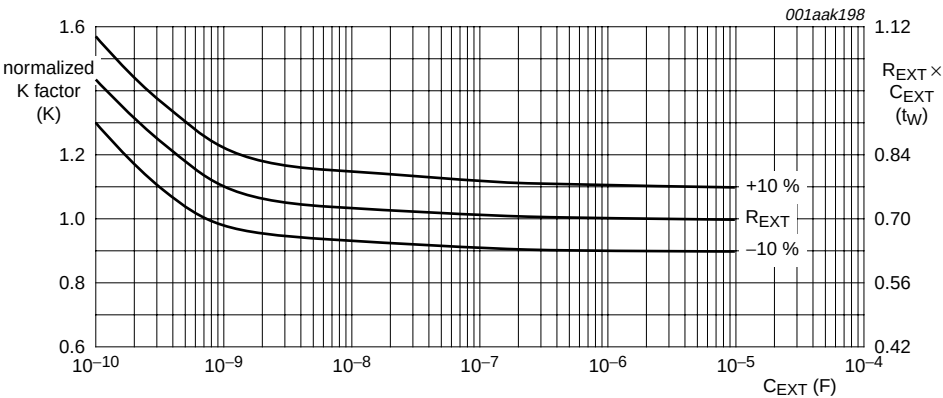


Fig 11. Typical pulse width accuracy versus external capacitance



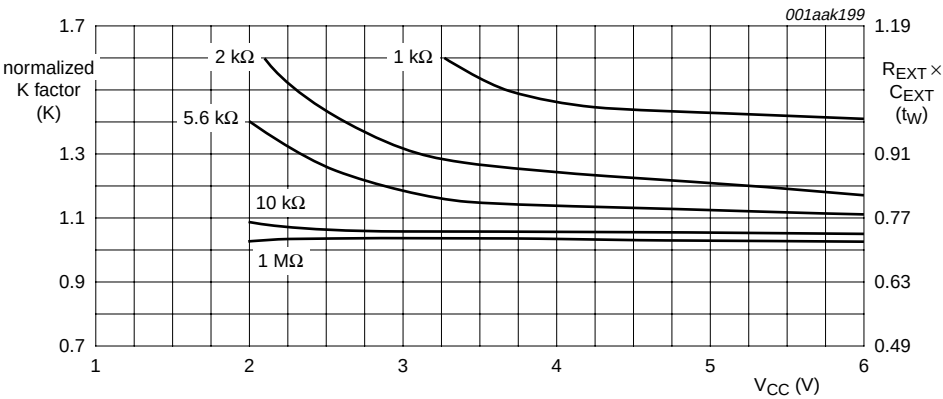
$V_{CC} = 4.5 \text{ V}$; $T_{amb} = 25 \text{ }^\circ\text{C}$.

Fig 12. Typical pulse width accuracy versus external resistance



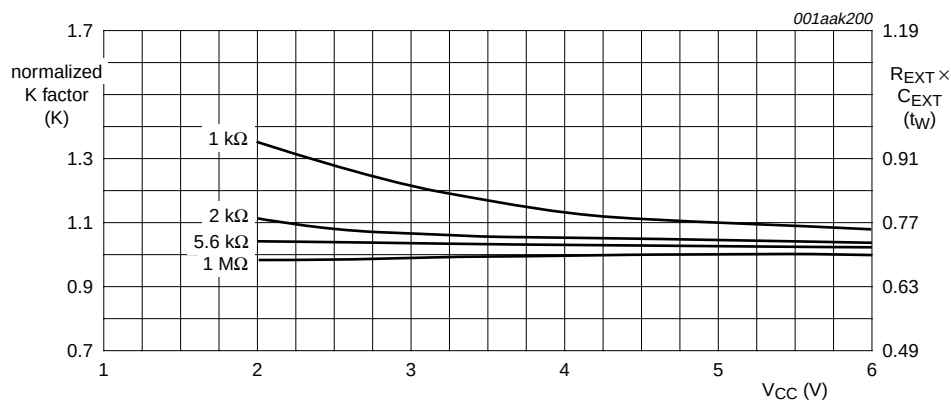
$V_{CC} = 4.5 \text{ V}$; $R_{EXT} = 10 \text{ k}\Omega$; $T_{amb} = 25 \text{ }^\circ\text{C}$.

Fig 13. Typical pulse width accuracy versus external capacitance



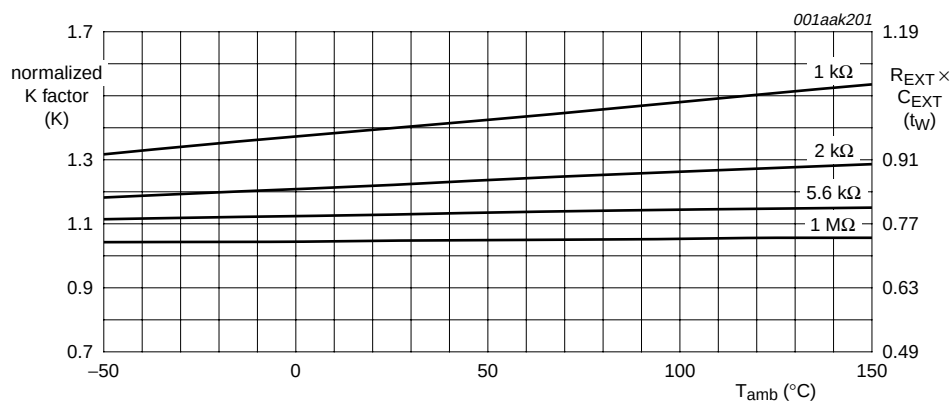
$C_{EXT} = 1 \text{ nF}$; $T_{amb} = 25 \text{ }^\circ\text{C}$.

Fig 14. Typical pulse width accuracy versus power supply



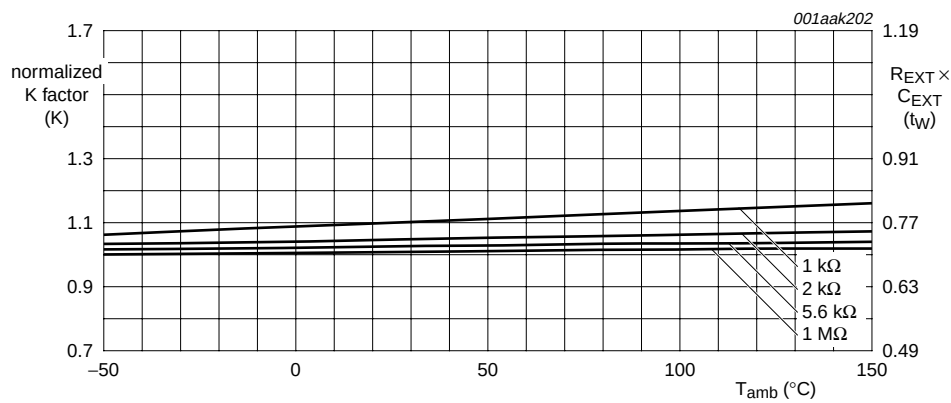
$C_{EXT} = 100 \text{ nF}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$.

Fig 15. Typical pulse width accuracy versus power supply



$V_{CC} = 4.5 \text{ V}$; $C_{EXT} = 1 \text{ nF}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$.

Fig 16. Typical pulse width accuracy versus temperature



$V_{CC} = 4.5 \text{ V}$; $C_{EXT} = 1 \text{ }\mu\text{F}$; $T_{amb} = 25 \text{ }^{\circ}\text{C}$.

Fig 17. Typical pulse width accuracy versus temperature

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

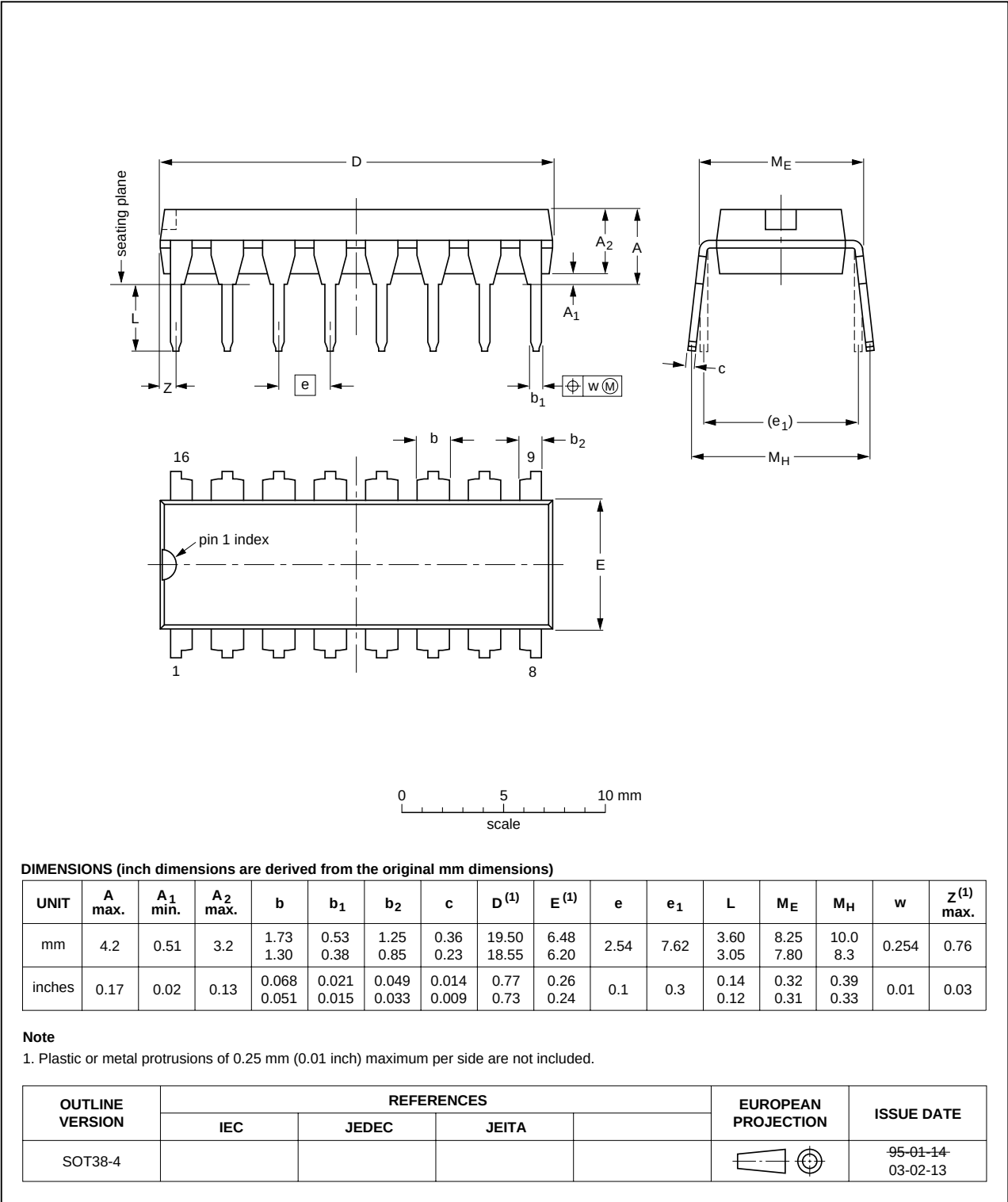
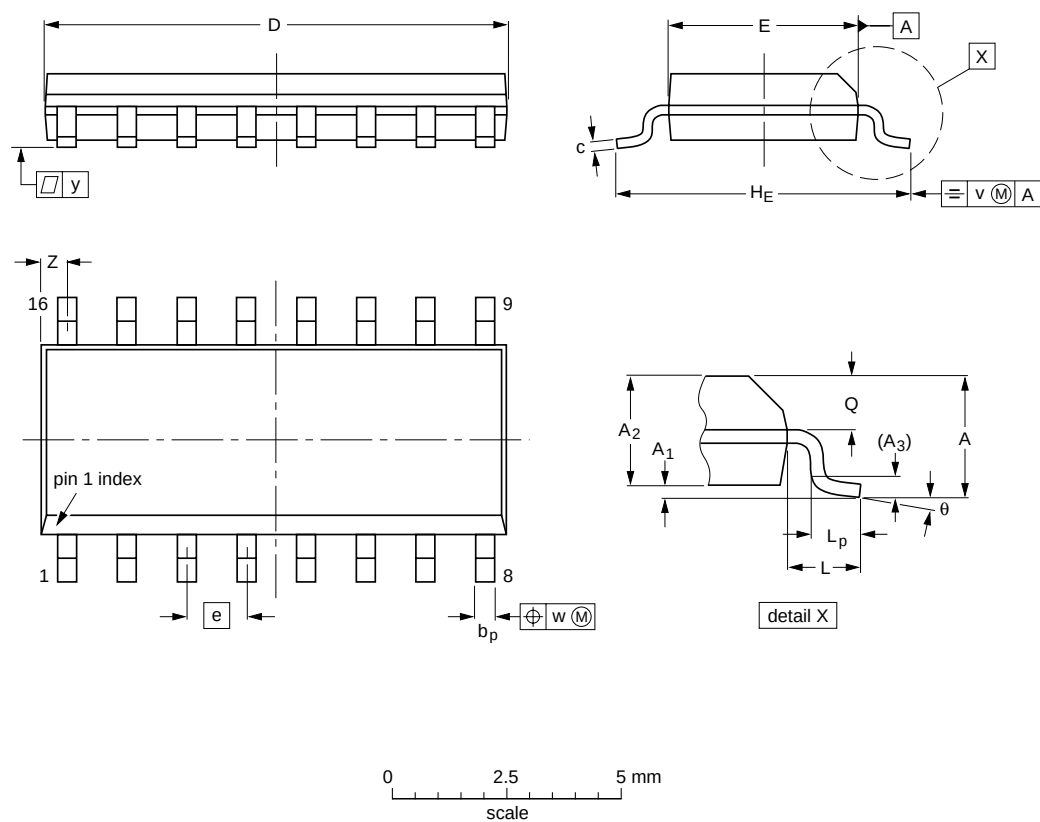


Fig 18. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	10.0 9.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.39 0.38	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.020	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT109-1	076E07	MS-012				99-12-27 03-02-19

Fig 19. Package outline SOT109-1 (SO16)

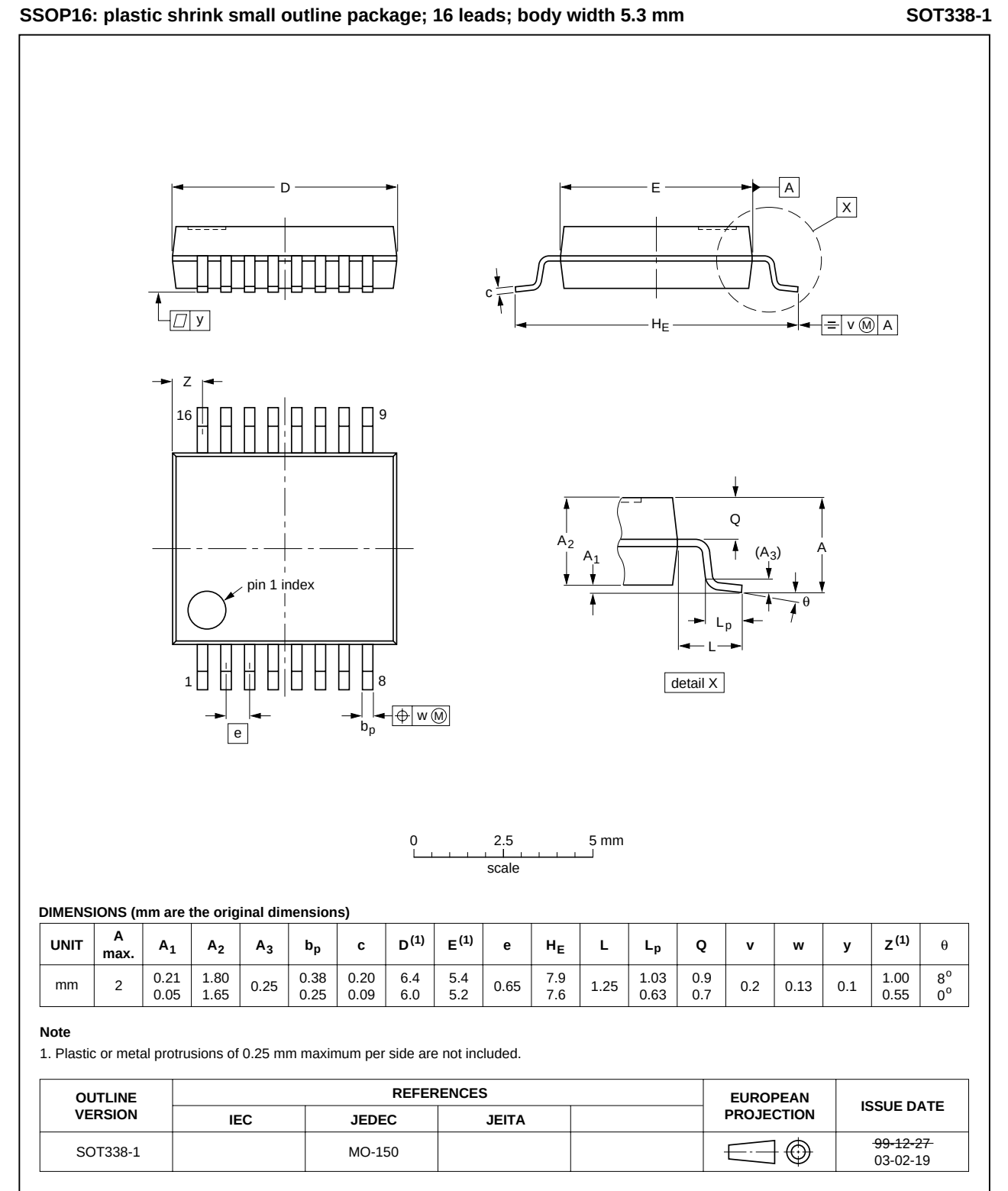


Fig 20. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

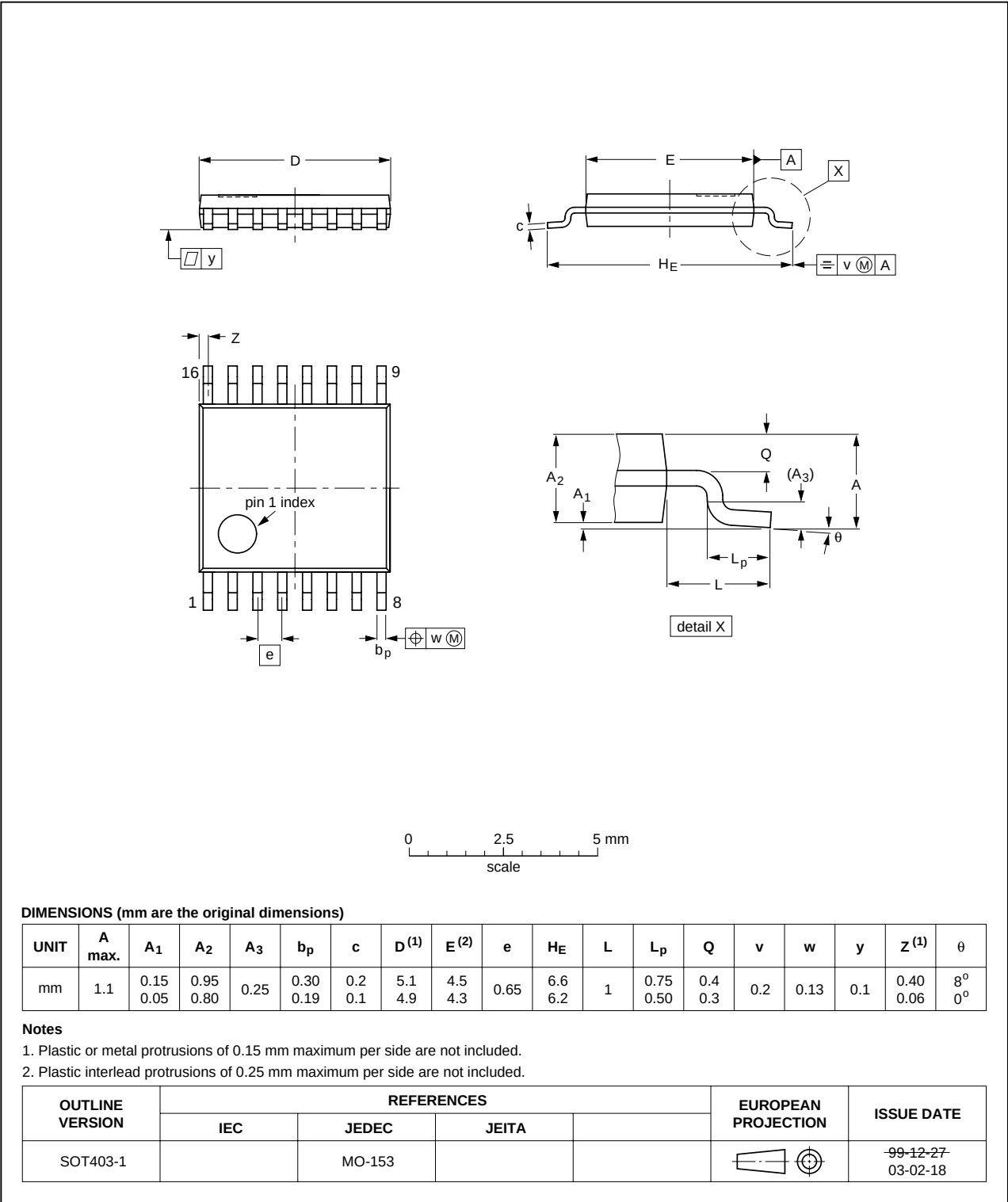


Fig 21. Package outline SOT403-1 (TSSOP16)

14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
LSTTL	Low-power Schottky Transistor-Transistor Logic
MM	Machine Model
TTL	Transistor-Transistor Logic

15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4538_3	20090608	Product data sheet	-	74HC_HCT4538_CNV_2
Modifications:	• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. • Pin names changed throughout. • Section Section 7, Section 8 and Section 9 added, taken from the 74HC/T HCMOS Family characteristics/specification (March 1988). • Test circuit added: Figure 9. • Quick reference data incorporated in to Section 9 and Section 10. • Package information added for DIP16, SO16, SSOP16 and TSSOP16 packages.			
74HC_HCT4538_CNV_2	19970902	Product specification	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

16.2 Definitions

Draft — The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Short data sheet — A short data sheet is an extract from a full data sheet with the same product type number(s) and title. A short data sheet is intended for quick reference only and should not be relied upon to contain detailed and full information. For detailed and full information see the relevant full data sheet, which is available on request via the local NXP Semiconductors sales office. In case of any inconsistency or conflict with the short data sheet, the full data sheet shall prevail.

16.3 Disclaimers

General — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use — NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in medical, military, aircraft, space or life support equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental

damage. NXP Semiconductors accepts no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications — Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

Limiting values — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) may cause permanent damage to the device. Limiting values are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of this document is not implied. Exposure to limiting values for extended periods may affect device reliability.

Terms and conditions of sale — NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, including those pertaining to warranty, intellectual property rights infringement and limitation of liability, unless explicitly otherwise agreed to in writing by NXP Semiconductors. In case of any inconsistency or conflict between information in this document and such terms and conditions, the latter will prevail.

No offer to sell or license — Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Export control — This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from national authorities.

16.4 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

17. Contact information

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

18. Contents

1	General description	1
2	Features	1
3	Ordering information	2
4	Functional diagram	2
5	Pinning information	4
5.1	Pinning	4
5.2	Pin description	4
6	Functional description	5
7	Limiting values	6
8	Recommended operating conditions	7
9	Static characteristics	7
10	Dynamic characteristics	9
11	Waveforms	12
12	Application information	15
12.1	Power-down considerations	15
12.2	Graphs	15
13	Package outline	18
14	Abbreviations	22
15	Revision history	22
16	Legal information	23
16.1	Data sheet status	23
16.2	Definitions	23
16.3	Disclaimers	23
16.4	Trademarks	23
17	Contact information	23
18	Contents	24

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

founded by

PHILIPS

© NXP B.V. 2009.

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 8 June 2009

Document identifier: 74HC_HCT4538_3

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:

moschip.ru

moschip.ru_4

moschip.ru_6

moschip.ru_9